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REMARKS

Before discussing the rejection over the prior art, Applicants deem it prudent to set forth what they consider to be their invention. Applicants' invention is directed to a method of coating a glass substrate which comprises:

- (a) providing a glass substrate;
- (b) applying to the glass substrate a coating composition comprising:
 - (1) from 1% to 98% by weight of a solventless, epoxy resin, reaction product of epichlorohydrin and at least one component selected from the group consisting of bisphenol A and bisphenol F, which reaction product is liquid at 20°C;
 - (2) from 1% to 98% by weight of a water-dilutable epoxy resin hardener;
 - (3) from 1% to 98% by weight of water; and
 - (4) optionally additives; and
- (c) curing the coating composition.

The application is also directed to a glass fiber coated with a cured composition of the invention. Applicants respectfully submit that the invention as presently claimed is neither taught nor suggested by the prior art reference cited by the Examiner.

The critical features of the invention is applying to the glass substrate a coating composition containing a solventless epoxy resin, a water-dilutable epoxy resin hardener and water. The composition of the present invention is neither taught nor suggested in the prior art reference cited by the Examiner.

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Claims 1, 4-6 and 8-12 stand rejected under 35 USC 102(b) as anticipated by Adam et al. (US 4,524,181 hereinafter Adam). Applicants respectfully submit that Adam neither teaches nor suggests the present invention.

Applicants have thoroughly perused Adam and can find no reference to a composition containing an epoxy resin reaction product of epichlorohydrin and at least one of bisphenol A and bisphenol F, a water-dilutable epoxy resin hardener and water. None of the text or the examples in Adam disclose a composition containing a water-dilutable epoxy resin hardener and water.

The Examiner cites col. 4, lines 28-30. At this point, Adam merely discloses a solventless, fluid epoxy resin composition that is storage stable against separation of phases for at least one year, and preferably for two years which is suitable for preparation of curable epoxy resin having reduced susceptibility to mechanical or thermal shock. The fluid epoxy resin composition disclosed in Adam comprises one part of a curable epoxide group-containing compound and 0.05 to 1 part of a colloiddally-dispersed elastomeric particles that are insoluble in the epoxide compound. The dispersion does not comprise the epoxy resin and water.

The Examiner then cites col. 13, lines 3-30 and Example 4. Col. 13, lines 3-30 is directed to the preparation of the epoxy resin composition containing colloiddally-dispersed elastomeric particle. There is no water contained in the composition and the solvent, tetrahydrofuran, is utilized to prepare the dispersion. Applicants submit that col. 13, lines 3-30 is directed to preparation of the colloiddal-dispersion of the elastomeric particles in the

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epoxy resin. Applicants submit that there is neither teaching nor suggestion that there is any water involved in the process since the process is carried out in a dry reaction flask (col. 13, line 3).

Example 4 is directed to the use of the composition of the Adam disclosure for the preparation of glass fiber composites. The epoxy resin containing the colloidal-dispersion of the elastomeric particles, was mixed with EPON 1001 as an epoxy additive and with parachloro phenyl-dimethyl urea and dicyandiamide as the curing agents. The mixture of the epoxy resin and the curing agent was coated on the glass fibers forming a composite containing 70% glass and 30% epoxy mixture and the composition was cured by heating to 121°C. The fracture energy of the sample containing the elastomeric particles and the sample coated with the resin which did not contain the elastomeric particles were compared. The sample containing the elastomeric particles had a fracture energy of about 20 times greater than the epoxy resin which did not contain the elastomeric particles. However, the composition utilized to coat the glass fibers was not a composition containing water or any suggestion that such a composition would be useful.

Applicants have examined the claims in Adam and did not find a single claim referring to any composition containing water.

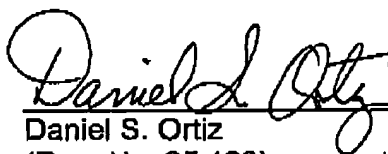
Applicants submit that to be a proper grounds of rejection under 35 USC 102(b), a reference must teach each and every limitation in the rejected claims. Applicants submit that Adam fails as a reference upon which a rejection under 35 USC 102(b) can be based since Adam neither teaches nor suggests a polymerizable composition containing a water-

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dilutable epoxy resin hardener, water and a solventless epoxy resin reaction product of epichlorohydrin and at least one component selected from the group consisting of bisphenol A and bisphenol F which is liquid at 20°C. Applicants therefor respectfully submit that Adam is not a proper reference and request that the rejection under the 35 USC 102(b) be reconsidered and withdrawn. Applicants also submit that Adam is not a proper reference on which a rejection under 35 USC 103(a) can be based since Adam is completely silent concerning a water-dilutable epoxy resin hardener and a composition containing epoxy resin, hardener and water.

Applicants therefore respectfully request favorable consideration and allowance of the claims.

Respectfully submitted,



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